



Material Content Data Sheet



Sales Product Name		IPG20N04S4L-18A		Issued		4. July 2019		
MA#		MA003168720						
Package		PG-TDSON-8-10		Weight*		97.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.562	0.57	0.57	5734	5734
chip_2	inorganic material	silicon	7440-21-3	0.562	0.57	0.57	5734	5734
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		142	
	non noble metal	iron	7439-89-6	0.046	0.05		474	
	non noble metal	copper	7440-50-8	46.380	47.36	47.42	473434	474050
	non noble metal	aluminium	7429-90-5	0.778	0.79	0.79	7946	7946
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		937	
	plastics	epoxy resin	-	6.514	6.65		66494	
	inorganic material	silicondioxide	60676-86-0	39.268	40.08	46.82	400837	468268
leadfinish	non noble metal	tin	7440-31-5	1.396	1.43	1.43	14254	14254
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.62	0.62	6156	6171
solder	non noble metal	tin	7440-31-5	0.035	0.04		357	
	noble metal	silver	7440-22-4	0.044	0.04		446	
	non noble metal	lead	7439-92-1	1.669	1.70	1.78	17040	17843
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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